

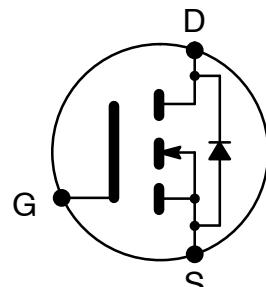


ELECTRONICS, INC.  
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**NTE2986**  
**Logic Level MOSFET**  
**N-Channel, Enhancement Mode**  
**High Speed Switch**  
**TO220 Type Package**

**Features:**

- Dynamic dv/dt Rating
- Logic Level Gate Drive
- $R_{DS(on)}$  Specified at  $V_{GS} = 4V$  &  $5V$
- $+175^{\circ}\text{C}$  Operating Temperature
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements



**Absolute Maximum Ratings:**

Drain Current, $I_D$	
Continuous ( $V_{GS} = 5V$ )	
$T_C = +25^{\circ}\text{C}$	..... 50A
$T_C = +100^{\circ}\text{C}$	..... 36A
Pulsed (Note 1)	..... 200A
Total Power Dissipation ( $T_C = +25^{\circ}\text{C}$ ), $P_D$	..... 150W
Derate Above $25^{\circ}\text{C}$	..... $1.0\text{W}/^{\circ}\text{C}$
Gate-Source Voltage, $V_{GS}$	..... $\pm 10V$
Single Pulsed Avalanche Energy (Note 2), $E_{AS}$	..... 110mJ
Peak Diode Recovery dv/dt (Note 3), dv/dt	..... 4.5V/ns
Operating Junction Temperature Range, $T_J$	..... $-55^{\circ}$ to $+175^{\circ}\text{C}$
Storage Temperature Range, $T_{stg}$	..... $-55^{\circ}$ to $+175^{\circ}\text{C}$
Maximum Lead Temperature (During Soldering, 1.6mm from case, 10sec), $T_L$	..... $+300^{\circ}\text{C}$
Mounting Torque, 6-32 or M3 Screw	..... 10 lbf-in (1.1 N•m)
Thermal Resistance:	
Maximum Junction-to-Case, $R_{thJC}$	..... 1.0K/W
Typical Case-to-Sink (Mounting surface flat, smooth, and greased), $R_{thCS}$	..... 0.5K/W
Maximum Junction-to-Ambient (Free Air Operation), $R_{thJA}$	..... 62K/W

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2.  $L = 179 \leq H$ ,  $V_{DD} = 25V$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 51A$ , Starting  $T_J = +175^{\circ}\text{C}$ .

Note 3.  $I_{SD} \leq 51A$ ,  $di/dt \leq 250A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq +175^{\circ}C$ .

Rev. 10-13

**Electrical Characteristics:** ( $T_C = +25^\circ\text{C}$  unless otherwise specified)

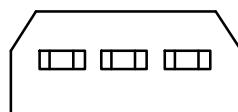
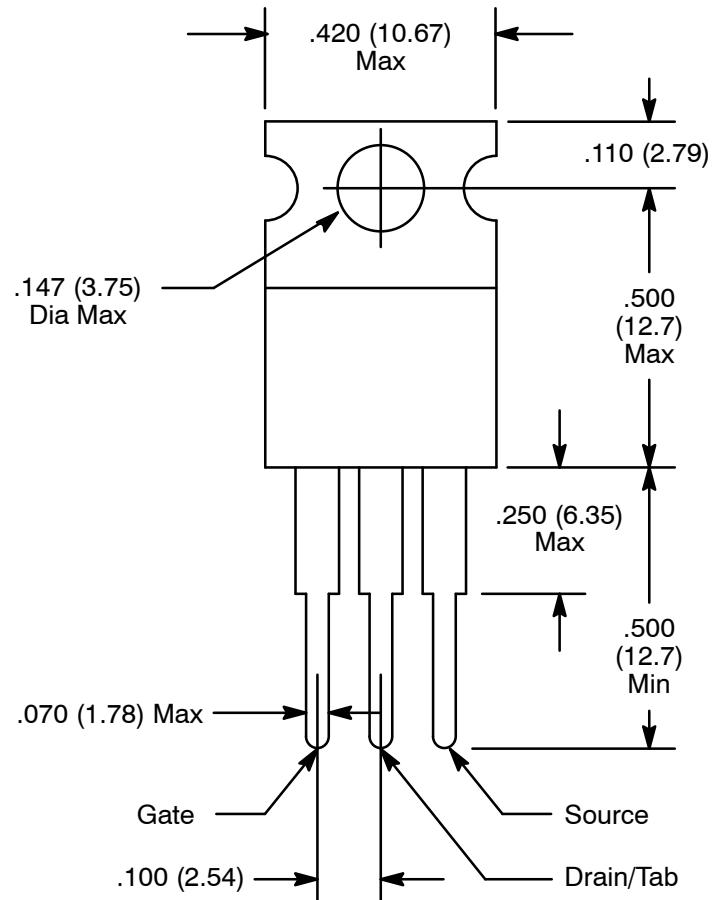
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}$ , $I_D = 250\text{mA}$	60	—	—	V
Breakdown Voltage Temperature Coefficient	$\pm V_{(\text{BR})\text{DSS}}/\pm T_J$	Reference to $+25^\circ\text{C}$ , $I_D = 1\text{mA}$	—	0.07	—	$\text{V}/^\circ\text{C}$
Static Drain–Source ON Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 5\text{V}$ , $I_D = 31\text{A}$ , Note 4	—	—	0.028	$\geq$
		$V_{\text{GS}} = 4\text{V}$ , $I_D = 25\text{A}$ , Note 4	—	—	0.039	$\geq$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250\text{nA}$	1.0	—	2.0	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} \geq 25\text{V}$ , $I_D = 31\text{A}$ , Note 4	23	—	—	mhos
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 60\text{V}$ , $V_{\text{GS}} = 0$	—	—	25	$\leq\text{A}$
		$V_{\text{DS}} = 48\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_C = +150^\circ\text{C}$	—	—	250	$\leq\text{A}$
Gate–Source Leakage Forward	$I_{\text{GSS}}$	$V_{\text{GS}} = 10\text{V}$	—	—	100	nA
Gate–Source Leakage Reverse	$I_{\text{GSS}}$	$V_{\text{GS}} = -10\text{V}$	—	—	-100	nA
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 5\text{V}$ , $I_D = 51\text{A}$ , $V_{\text{DS}} = 48\text{V}$	—	—	66	nC
Gate–Source Charge	$Q_{\text{gs}}$		—	—	12	nC
Gate–Drain (“Miller”) Charge	$Q_{\text{gd}}$		—	—	43	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}$ , $I_D = 51\text{A}$ , $R_G = 4.6\text{M}\Omega$ , $R_D = 0.56\text{M}\Omega$	—	17	—	ns
Rise Time	$t_r$		—	230	—	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		—	42	—	ns
Fall Time	$t_f$		—	110	—	ns
Internal Drain Inductance	$L_D$	Between lead, 6mm (0.25") from package and center of die contact	—	4.5	—	nH
Internal Source Inductance	$L_S$		—	7.5	—	nH
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}$ , $V_{\text{DS}} = 25\text{V}$ , $f = 1\text{MHz}$	—	3300	—	pF
Output Capacitance	$C_{\text{oss}}$		—	1200	—	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		—	200	—	pF

**Source–Drain Diode Ratings and Characteristics**

Continuous Source Current	$I_S$	(Body Diode)	—	—	50	A
Pulse Source Current	$I_{\text{SM}}$	(Body Diode) Note 1	—	—	200	A
Diode Forward Voltage	$V_{\text{SD}}$	$T_J = +25^\circ\text{C}$ , $I_S = 51\text{A}$ , $V_{\text{GS}} = 0\text{V}$ , Note 4	—	—	2.5	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +25^\circ\text{C}$ , $I_F = 51\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ , Note 4	—	130	180	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		—	0.84	1.3	$\mu\text{C}$
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ )				

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 4. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .



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